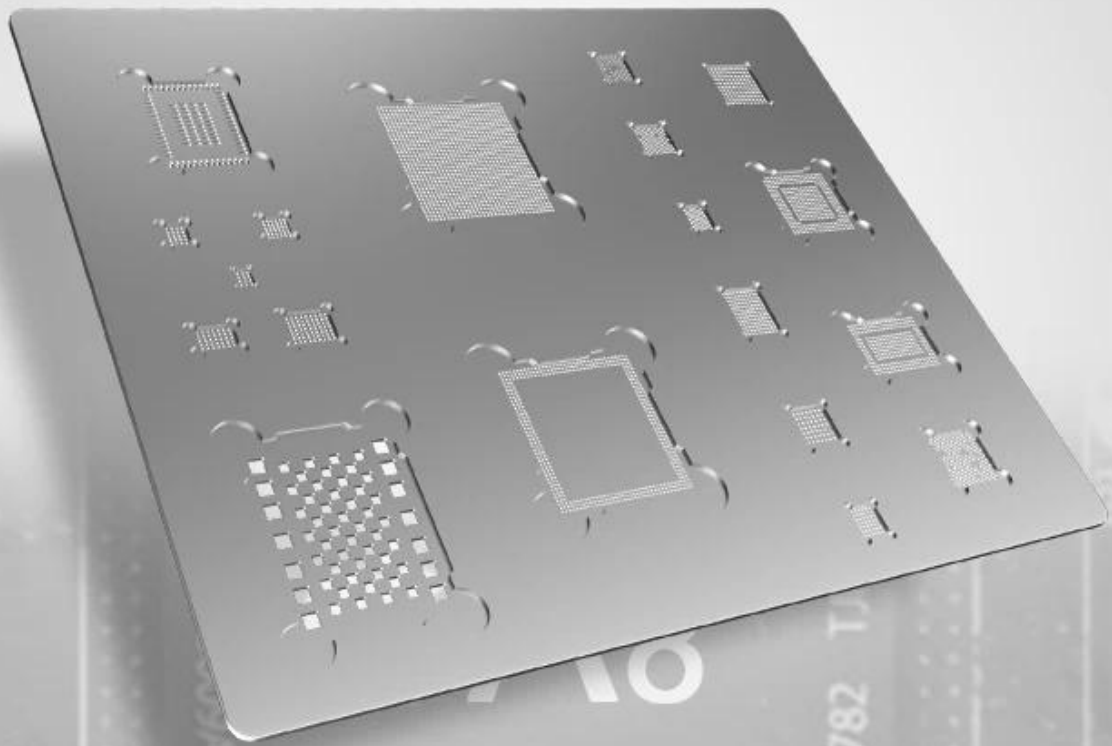


A8 BGA IC Reballing Iphone 6 6P Ipod touch 6 Ipad mini4

- iPhone 6 Plus BGA x 1
- iPhone 6 BGA x 1
- ipod touch 6 BGA Reballing x 1
- iPad mini4 BGA x 1

3D GROOVE

— REBALLING STENCIL —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

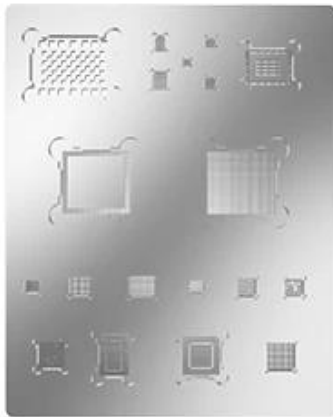


PRECISE ALIGNMENT



SQUARE HOLE

Product Usage



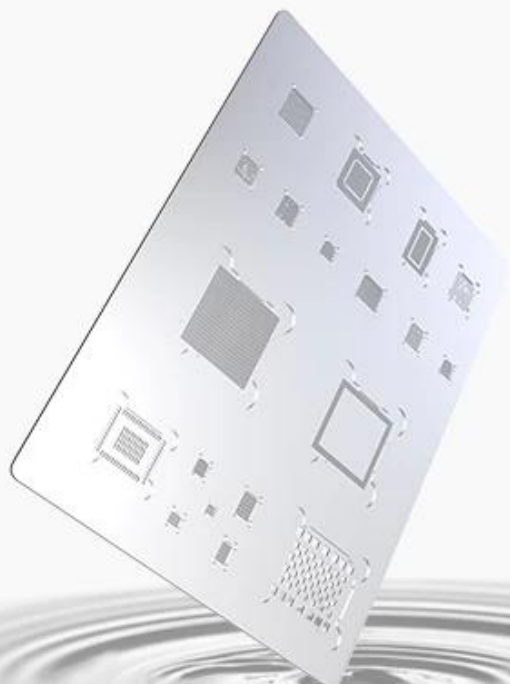
MODEL	A8
WEIGHT	18.6g
MATERIAL	imported steel
SIZE	68.9 X 84.9mm
MATCHING MACHINE TYPE	iPhone6/Plus/ iPod Touch6/iPad mini4

▼ CHARACTERISTICS

This product is used for BGA tinning repair of the iPhone6/Plus/iPod Touch6/iPad mini4 series. Imported steel, anti-rolling anti-deformation, automatic alignment, accurate hole position, non-stick tin, good toughness, good off-grid.

IMPORTED STEEL

HIGH TOUGHNESS



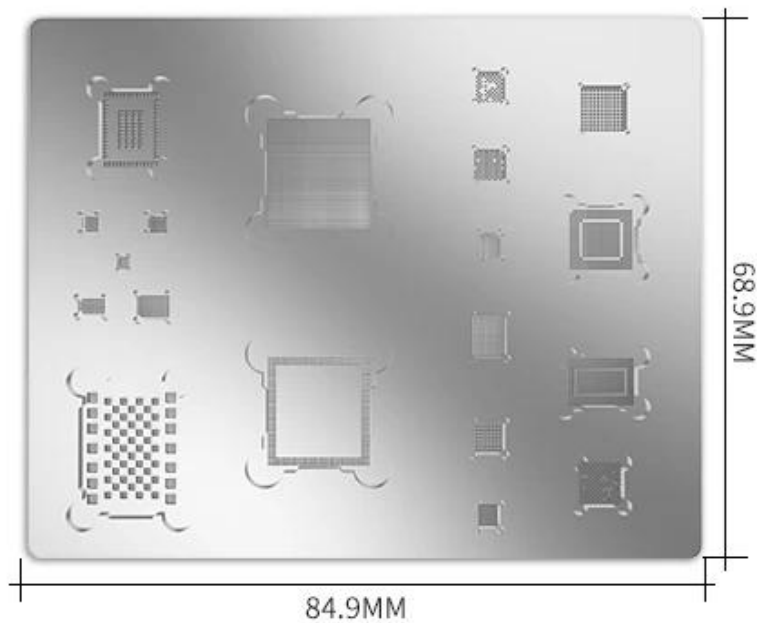
Easily mounted on the steel mesh to make the chip fit more closely with the mesh
Therefore, the chip after tinning is "more precise"





Imported steel
Hard and wear resistant
Accurate to the hole

PRODUCT SIZE



Thin to 0.30mm

Precise die-casting **form heating**



